

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YU-LIANG WU	08/26/2020
XING WEI	08/26/2020
TAK-KEI LAM	08/26/2020
YI DIAO	08/26/2020
RECEIVING PARTY DATA	
Name:	EASY-LOGIC TECHNOLOGY LTD.
Street Address:	UNIT 225, BUILDING16W,
Internal Address:	HONG KONG SCIENCE PARK, SHATIN
City:	HONG KONG
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17005337
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	EAGLE IP LIMITED
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Address Line 2:	LAI CHI KOK,
Address Line 4:	HONG KONG, CHINA
ATTORNEY DOCKET NUMBER:	E023.002.CIPUS2
NAME OF SUBMITTER:	JACQUELINE C.LUI
SIGNATURE:	/Jacqueline C. Lui/
DATE SIGNED:	08/31/2020
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, We,

WU, Yu-Liang, a Hong Kong resident, located at Unit 225, Building 16W, Hong Kong Science Park, Shatin, Hong Kong, China;

LAM, Tak-Kei, a Hong Kong resident, located at Unit 225, Building 16W, Hong Kong Science Park, Shatin, Hong Kong, China;

WEI, Xing, a Hong Kong resident, located at Unit 225, Building 16W, Hong Kong Science Park, Shatin, Hong Kong, China; and

DIAO, Yi, a Hong Kong resident, located at Unit 225, Building 16W, Hong Kong Science Park, Shatin, Hong Kong, China (hereinafter "Assignors"), made certain new and useful inventions and improvements (hereinafter "Inventions and Improvements") that have been documented in a specification entitled "Methods and Apparatus for Removing Functional Bugs and Hardware Trojans for Integrated Circuits Implemented by Field Programmable Gate Array (FPGA)"; for which We have executed application for patent in the United States (hereinafter "Application")

filed on 28 Aug 2020 under serial number 17005337;
(in the event that the filing date and/or Serial No. are not entered at the time We execute this document, and if such information is deemed necessary, We hereby authorize and request our attorneys at EAGLE IP LIMITED of Room 508-509 Global Gateway Tower, 63 Wing Hong Street, Lai Chi Kok, Hong Kong, to insert above the filing date and Serial No. of said application when known.)

AND WHEREAS, Easy-Logic Technology Ltd., a limited company, organized and existing under and by virtue of the laws of Hong Kong S.A.R. China, and having an office and place of business at Unit 225, Building 16W, Hong Kong Science Park, Shatin, Hong Kong, China (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said Inventions and Improvements and said Application and in and to the patent to be obtained therefrom;

NOW THEREFORE, to all whom it may concern, be it known that in consideration of One Dollar (USD 1.00), and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, We have sold, assigned, and transferred, and by these present do sell, assign and transfer unto said Assignee, its successors, legal representatives or assigns, the entire right, title and interest for all countries in and to all inventions disclosed in said Application, and in and to the said Application, all divisions, continuations or renewals thereof, all patents which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any country or countries foreign to the United States for patents on said Inventions and Improvements, including an assignment of all rights under the provisions of the International Convention, and all patents of any country or countries foreign to the United States which may be granted therefrom; and We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue any and all United States Patents, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue any and all patents, for the said Inventions and Improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of said Assignee, its successors, legal representatives and assigns.

AND, for the consideration aforesaid, We do hereby agree that We and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors, legal representatives and assigns all facts known to us relating to said Inventions and Improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors, legal representatives or assigns the entire right, title and interest in and to the said Inventions and Improvements, Application, patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore We covenant and agree with said Assignee, its successors, legal representatives or assigns, that no assignment, grant, mortgage license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

SIGNED this 26th day of Aug, 2020 in Hong Kong, China
(month) (year) (city) (country)

B023.002.CIPUS2

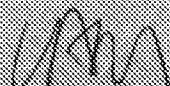
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Name Printed: WEI, Xing

Title: Chief Executive Officer

PATENT

RECORDED: 08/31/2020

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